



Product Change Notification - LIAL-26JKUB646

Date:

01 Jan 2019

Product Category:

32-bit Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3300, 3300.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18 μm wafer technology available in 100L and 64L TQFP packages at MTAI assembly site.

Notification text:**PCN Status:**

Final notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18 μm wafer technology available in 100L and 64L TQFP packages at MTAI assembly site

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand HQ (MTAI)	Microchip Technology Thailand HQ (MTAI)
Wire material	Au	CuPdAu
Die attach material	3280	3280
Molding compound material	G700HA	G700HA
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 01, 2019 (date code: 1906)



NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2018					>	January 2019					February 2019			
Workweek	9	10	11	12	13		01	02	03	04	05	06	07	08	09
Initial PCN Issue Date					X										
Qual Report Availability							X								
Final PCN Issue Date							X								
Estimated Implementation Date												X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

March 29, 2018: Issued initial notification.

January 01, 2019: Issued final notification. Attached the qualification report and provided estimated first ship date to be on February 01, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN LIAL-26JKUB646 Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PIC32MX350F128H-I/PT
PIC32MX350F128HT-I/PT
PIC32MX350F128HT-V/PT
PIC32MX350F128H-V/PT
PIC32MX350F256H-I/PT
PIC32MX350F256HT-I/PT
PIC32MX350F256HT-V/PT
PIC32MX350F256H-V/PT
PIC32MX450F128H-I/PT
PIC32MX450F128HT-I/PT
PIC32MX450F128HT-V/PT
PIC32MX450F128H-V/PT
PIC32MX450F256H-120/PT
PIC32MX450F256H-I/PT
PIC32MX450F256H-I/PTB21
PIC32MX450F256HT-120/PT
PIC32MX450F256HT-I/PT
PIC32MX450F256HT-V/PT
PIC32MX450F256H-V/PT
PIC32MX350F128L-I/PT
PIC32MX350F128LT-I/PT
PIC32MX350F128LT-V/PT
PIC32MX350F128L-V/PT
PIC32MX350F256L-I/PT
PIC32MX350F256LT-I/PT
PIC32MX350F256LT-V/PT
PIC32MX350F256L-V/PT
PIC32MX450F128L-I/PT
PIC32MX450F128LT-I/PT
PIC32MX450F128LT-V/PT
PIC32MX450F128L-V/PT
PIC32MX450F256L-120/PT
PIC32MX450F256L-I/PT
PIC32MX450F256LT-120/PT
PIC32MX450F256LT-I/PT
PIC32MX450F256LT-V/PT
PIC32MX450F256L-V/PT